

C0805C102KAGECTU

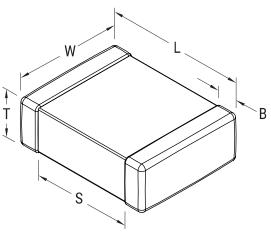
Aliases (C0805C102KAGEC7800)

ESD SMD Comm COG, Ceramic, 1,000 pF, 10%, 250 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805, 0.7 mm

ESD SMD Comm COG

SMD, MLCC, Temperature Stable, Electro Static Discharge,

SMD Chip



В	Features	Temperature Stable, Low ESR, Class I
	RoHS	Yes
	Termination	Tin
s	Marking	No
	AEC-Q200	No
Click here for the 3D model.	Typical Component Weight	13 mg
	Shelf Life	78 Weeks
	MSI	1

General Information

Series Style

Description

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Specifications	
Capacitance	1,000 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	250 VDC
ESD Level per AEC-Q200	8,000 V ESD Level
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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